

SEP 23 2005

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BULLET POINTS FOR INTERVIEW SCHEDULED FOR 9/27/05 @ 10 AM

Application No.:	10/766,210
Filing Date:	January 29, 2004
Applicant:	Yong-Kwan LEE
Group Art Unit:	2818
Examiner:	Tu Tu V. Ho
Title:	FLIP CHIP PACKAGE HAVING PROTECTIVE CAP AND METHOD OF FABRICATING THE SAME
Attorney Docket:	2557-000202/US

Examiner Ho,
 Further to your conversation on 9/19/05 with associate Daniel Podhajny, please find enclosed a summary of topics for discussions for interview, proposed specification and drawing amendments and a proposed claim amendment for the Examiner interview scheduled for 9/27/05 @ 10 AM with Daniel Podhajny and Matthew Lattig (Reg. #45,274).

*Matthew Lattig*Summary of Interview Agenda

- Discuss proposed Amendment to specification (attached) for overcoming the drawing and claim objections.
- Discuss proposed Claim amendment to overcome the 35 U.S.C. § 103(a) rejection to Caletka in view of Yoshikawa
 - Argue that the limitations of claim 8, which have been included in the proposed independent claim 1, are allowable over Caletka in view of Yoshikawa.
 - Caletka does not disclose or suggest "an adhesion layer". At most, Caletka discloses a resin layer 26/226/526/726 (See each of figures 1 – 5A, 6B, 8A, 9A).
 - Thus, Caletka cannot disclose both of a "molding resin layer" and an "adhesion layer", as recited in proposed independent claim 1, because Caletka's disclosure is limited to a single layer, and not two separate layers, as we recite in claim 1.
 - Likewise, Yoshikawa does not disclose this feature. In Yoshikawa, solder balls 5 are attached to a substrate 4 which is connected to electrodes 6. The electrodes 6 connect to a LSI chip 3 which connects to a heat sink 1. A single mold resin 2 surrounds the LSI chip 3 under the heat sink 6.